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Francis J. Downes et al.

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**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5,072,075	12/1991	Lee et al.			
	5,121,190	6/1992	Hsiao et al.			
	5,483,421	1/1996	Gedney et al.			
	5,574,630	11/1996	Kresge et al.			
	5,615,087	3/1997	Wieloch			
	5,798,563	8/1998	Feilchenfeld et al.			
	5,894,173	4/1999	Jacobs et al.			
	5,900,675	5/1999	Appelt et al.			
	4,882,454	11/1989	Peterson et al.			
	5,982,630	11/1999	Bhatia			
	5,926,377	7/1999	Nakao et al.			

10/06/95  
10/06/95  
02/05/02**FOREIGN PATENT DOCUMENTS**

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
	9-232376	9/1997	Japan				
	10-209347	8/1998	Japan				
	11-87560	3/1999	Japan				
	2000-22071	1/2000	Japan				
	6-112271	4/1994	Japan				

**OTHER DOCUMENTS** (Including Author, Title, Date, Pertinent Pages, Etc.)

		IBM Technical Disclosure Bulletin, Vol. 32, No. 3B, August 1989, "MULTILAYER POLYMER SUBSTRATE FOR DIRECT CHIP ATTACHMENT."
		PROCESS CONSIDERATIONS IN THE FABRICATION OF TEFLON PRINTED CIRCUIT BOARDS, Light et al., 1994 Proceedings, 44 Electronic Components & Technology Conference, 5/94.

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		5,661,089	8/1997	Wilson			

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
		2000-24150	1/2000	Japan				
		1-307294	12/1989	Japan				

**OTHER DOCUMENTS** (Including Author, Title, Date, Pertinent Pages, Etc.)

			HIGH PERFORMANCE CARRIER TECHNOLOGY: MATERIALS AND FABRICATION, Light et al., 1993 International Electronics Packaging Conference, San Diego, CA Volume One.
			HIGH PERFORMANCE CARRIER TECHNOLOGY, Heck et al., 1993 International Electronics Packaging Conference, San Diego, CA, Volume One.

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DATE CONSIDERED

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